

Fig. 1. Two scenarios for orthogonal area selective deposition of two materials in a sequence

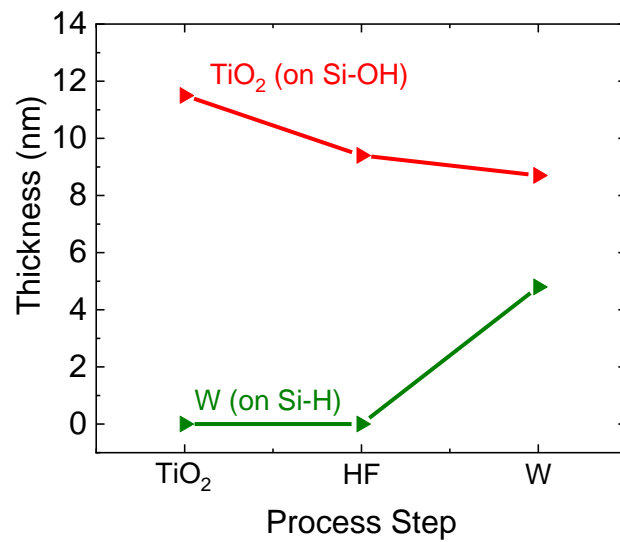


Fig. 2. Measured thickness of TiO₂ and W film on non-patterned Si-OH and Si-H substrates after each step (TiO₂ ASD, HF dip, W ASD) by spectroscopic ellipsometry.